

Littelfuse, Inc.  
8755 West Higgins Road, Suite 500  
Chicago, IL 60631 USA  
(773) 628-1000

---

May 19, 2021

## PCN1095

**Product Change Notification for Littelfuse Power Solid State Relays packaged in I4-PAC, ISOPLUS-264, and Super SIP DCB-based assemblies.**

## Detailed Description of Change

IXYS Integrated Circuits Division (ICD), now part of Littelfuse, is changing the mold compound used for our i4-PAC, ISOPLUS-264, and Super SIP packages. The mold compound for the i4-PAC and ISOPLUS-264 packages is changing from the Samsung SL-7300JX to the Panasonic CV8400ZVS. The Super SIP package mold compound is changing from the Shin-Etsu KMC-2380G to the Panasonic CV8400ZVS.

There is no impact on quality or reliability and no data sheet changes.

Parts numbers of the affected devices are listed below.

CPC1708J	CPC1779J	CPC1918J	CPC1978J	CPC40055ST
CPC1709J	CPC1786J	CPC1927J	CPC1979J	
CPC1718J	CPC1788J	CPC1967J	CPC1986J	
CPC1727J	CPC1908J	CPC1968J	CPC1988J	
CPC1777J	CPC1909J	CPC1977J	CPC1998J	

These changes are effective immediately.

The PCN number assigned to this action is **PCN1095** and must be referenced in any correspondence related to the change.

## Contact Information

For any questions related to this PCN notice, please contact Littelfuse, IXYS Integrated Circuits Division's Customer Service Department as indicated below:

### Martha W. Brandt

Senior Quality Engineer

IXYS Integrated Circuits Division

78 Cherry Hill Drive

Beverly, MA 01915

[mbrandt@littelfuse.com](mailto:mbrandt@littelfuse.com)

[envrequests-ixys@littelfuse.com](mailto:envrequests-ixys@littelfuse.com)

[www.ixysic.com](http://www.ixysic.com)

<https://www.ixysic.com/home/pages.nsf/req.cs>